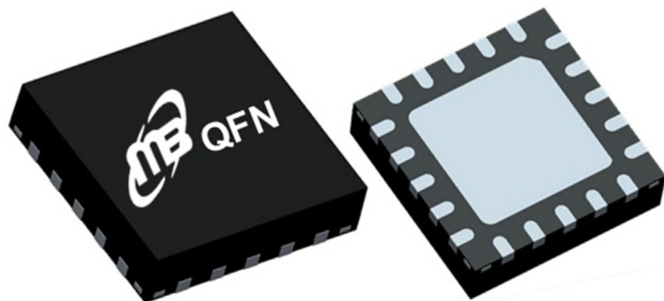
Quad Flat No-lead Package



Applications：

- Power Management, High Thermal Conductive Devices
- RF, Switch Devices
- Logic, Analog, and Sensors,
- Industry Micro-Controller

Features:

- Customized package size and leads in limited body size (1~10mm)
- Au, Cu, Ag-alloy, Al bonding process capabilities
- Multi-chip capability for stack or flat lie
- Component surface mount capability
- SiP assembly capability
- PPF or pure tin surface finish is optional

Reliability Condition:

- Moisture Sensitivity Pre-condition :
  -MSL3: 192hrs@30ºC/60% RH
  -MSL1: 168hrs@85ºC/85% RH
- Temperature Cycle: 500 cycles @ -65ºC /+150ºC
- Highly Accelerated Temp and Humidity Stress Test: 96hrs @130ºC/85% RH
- High Temperature Storage: 1000hrs@150ºC

Package Outlines Dimensions:

Frame Layout (mm)	Standard L/F Thickness (mm)	Mold Cap Thickness (mm)	Standard Pkg Thickness (mm)	Min Lead Pitch (mm)
189*68 2 Block	0.125 0.150 0.200	0.375 0.550 0.750	0.500 0.750 0.950	0.4

Notes: Package Size and Thickness is able customized , Do not limited above list

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